

# 800V N-Channel MOSFET

### **Description**

#### 800V N-Channel MOSFET

VDMOSFET is a double-diffusion device which the current flows is vertically, and is a voltage-controlled device. Under the control of the appropriate gate voltage, the semiconductor surface is inverted, forming a conductive channel and an appropriate amount of current flows between Drain and Source. Compared with bipolar transistor, its switching speed and switching loss are small. High input impedance, low driving power, good frequency characteristics, In particular, it has a negative temperature coefficient.

#### **Features**

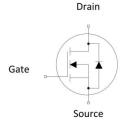
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### **Applications**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction(PFC)

TO-220F







### **Device Marking and Package Information**

Device	Package	Marking
TMA7N80H	TO-220F	A7N80H



<b>Absolute Maximum Ratings</b> T <sub>C</sub> = 25°C, unless	otherwise noted		
Parameter	Symbol	Values	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	800	V
Continuous Drain Current	I <sub>D</sub>	7	Α
Pulsed Drain Current (note	) I <sub>DM</sub>	28	Α
Gate-Source Voltage	V <sub>GSS</sub>	±30	V
Single Pulse Avalanche Energy (note:	E <sub>AS</sub>	156.8	mJ
Avalanche Current (note:	) I <sub>AR</sub>	5.6	Α
Repetitive Avalanche Energy (note	) E <sub>AR</sub>	147	mJ
Power Dissipation For TO-220F	P <sub>D</sub>	25	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

Thermal Resistance For TO-220F			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	5	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	5



		Value	/alue			
Parameter	Symbol	Symbol Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	800			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 800V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V			±100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0		4.0	V
Drain-SourceOn-State-Resistance (Note3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.5A		1.35	1.6	Ω
Dynamic Characteristics						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V$ ,		950		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25V$ ,		190		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		27		
Total Gate Charge	$Q_g$	49	49			
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 640V,$ $I_{D} = 7A,$		6		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> = 10V		26		
Turn-on Delay Time	t <sub>d(on)</sub>			43		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 400V$ ,		28		- ns
Turn-off Delay Time	$t_{d(off)}$	$I_D = 7A$ , $R_G = 25 \Omega$		244		
Turn-off Fall Time	t <sub>f</sub>			54		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I <sub>S</sub>	T 0500			7	A
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			28	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}$ , $I_{SD} = 3.5\text{A}$ , $V_{GS} = 0\text{V}$			1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_S = 7A,$		1090		ns
Reverse Recovery Charge	$Q_{rr}$	di <sub>F</sub> /dt =100A /μs 1.7		μC		

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics

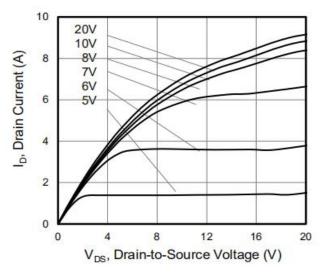


Figure 3. Drain Current vs. Temperature

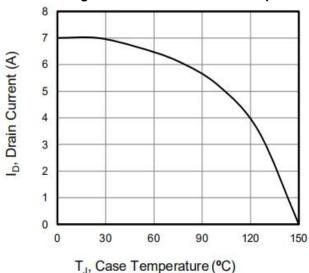


Figure 5. Transfer Characteristics

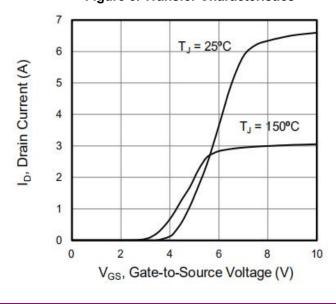


Figure 2. Body Diode Forward Voltage

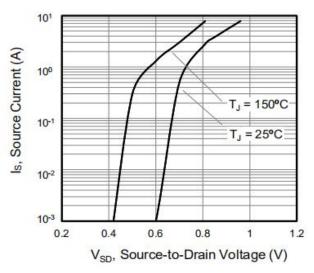


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

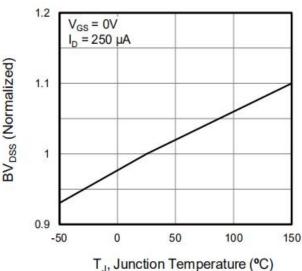
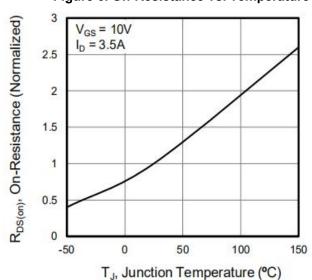
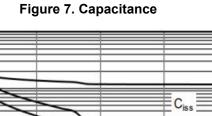


Figure 6. On-Resistance vs. Temperature



# **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted



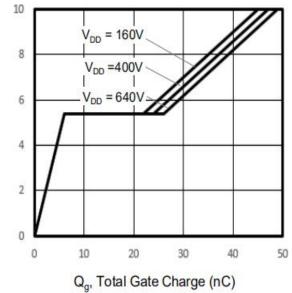
104 Capacitance (pF) 10<sup>3</sup> 10<sup>2</sup> Coss Crss 101  $V_{GS} = 0V$ f = 1MHz10°

20

V<sub>DS</sub>, Drain-to-Source Voltage (V)

30

Figure 8. Gate Charge



Ves, Gate-to-Source Voltage (V)

40



Figure A: Gate Charge Test Circuit and Waveform

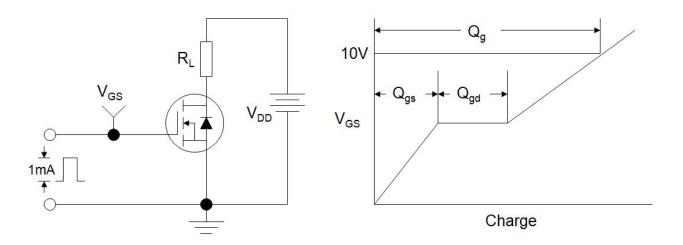


Figure B: Resistive Switching Test Circuit and Waveform

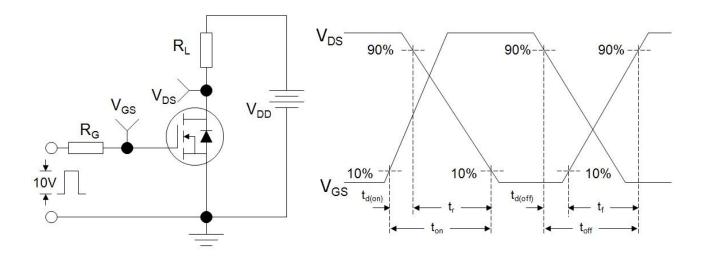
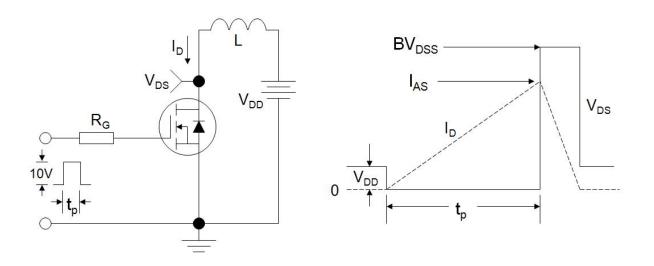
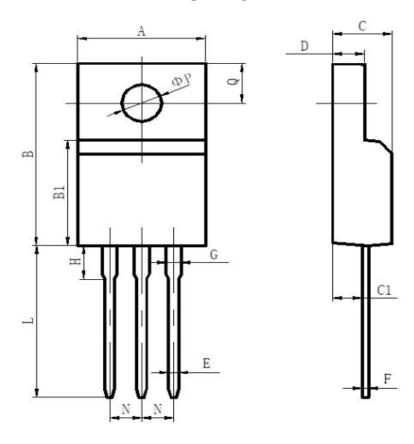


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





**TO-220F** 



项目	规范(mm)	
	MIN	MAX
A	9.70	10.30
В	15.50	16.10
BI	8.99	9.39
С	4.40	4.80
C1	2.15	2.55
D	2.50	2.90
Е	0.70	0.90
F	0.40	0.60
G	1.12	1.42
Н	3.40	3.80
L	12.6	13.6
N	2.34	2.74
Q	3.15	3.55
фР	3.00	3.30



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